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(Signature & date)

In application of \_\_\_\_\_:

January 29, 2004

Tien-Jen Cheng, et al. :

Group Art Unit: Not yet assigned

Serial No.10/707,892:

Examiner: Not yet assigned

Filed: 1/21/04 :

International Business Machines Corporation  
2070 Route 52  
Hopewell Junction, NY 12533

**TITLE:     **DEVICE WITH AREA ARRAY PADS FOR TEST PROBING****

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. 1.56, and further pursuant to the provisions of 37 C.F.R. 1.97 and 1.98, applicants hereby respectfully submit copies of the non-US patents and publications as listed on Form PTO-1449, attached hereto.

In citing these documents, no representation is made nor intended as to the pertinency or non-pertinency of the art, that better art than that listed is not available, or that other art is not applicable.

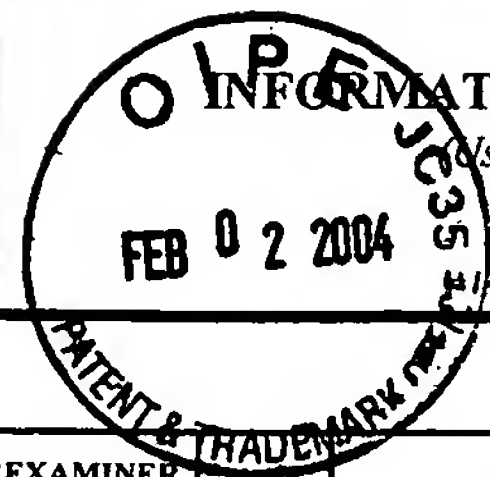
No fee is believed to be due for this submission. If any fees are required, however, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 09-0458.

Respectfully submitted,  
Tien-Jen Cheng, et al.

By \_\_\_\_\_

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FIS920030352US1



INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

FIS920030352US1

Application Number

10/707,892

Applicant(s)

TIEN-JEN CHENG, ET AL.

Filing Date

1/21/04

Group Art Unit

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
		JP9036169	2/07/97	JAPAN				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

		IBM Technical Disclosure Bulletin, HERDZIK ET AL., Gold-Nickel Plated Copper Ball Contacts For Microelectronic Devices, 8/1/1965, Page(s) 452, Volume 8, Number 3, Published in: USA

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.